

In the Claims:

1-12. (Canceled).

13. (Currently Amended) An integrated circuit package comprising:
a substrate having a plurality of conductive traces;
a plurality of balls disposed on a first surface of said substrate, such that said plurality of balls are electrically connected to said plurality of conductive traces;
a semiconductor die mounted to said substrate, such that bumps of said semiconductor die
[[are]] is electrically connected to said plurality of conductive traces of said substrate;
an overmold material encapsulating said semiconductor die and said balls on said substrate
such that portions of said balls that are disposed farthest from said substrate are exposed at an
exterior of said integrated circuit package; and
a ball grid array disposed on a second surface of said substrate and in electrical connection
with said conductive traces.

14. (Canceled).

15. (Previously presented) The integrated circuit package according to claim 13, wherein
said plurality of balls is attached to respective solder ball pads on said first surface of said substrate.

16. (Original) The integrated circuit package according to claim 13, wherein said bumps of
said semiconductor die are electrically connected to said conductive traces by wire bonds.

17. (Original) The integrated circuit package according to claim 13, wherein said
semiconductor die is fixed to said first surface of said substrate.

18. (Withdrawn) The integrated circuit package according to claim 26, further comprising a metal strip, wherein a first surface of said metal strip is laminated to said second surface of said substrate.

19. (Withdrawn) The integrated circuit package according to claim 18, wherein said semiconductor die is mounted to said first surface of said metal strip in a cavity in said substrate such that said semiconductor die is mounted to said substrate via said metal strip.

20. (Original) The integrated circuit package according to claim 13, wherein said plurality of balls circumscribe said semiconductor die.

21. (Canceled).

22. (Original) The integrated circuit package according to claim 13, wherein said balls are deformed.

23. (Original) The integrated circuit package according to claim 13, further comprising a die adapter mounted on said semiconductor die and encapsulated in said overmold material.

24. (Canceled).

25. (Original) The integrated circuit package according to claim 13, wherein said plurality of balls is comprised of a plurality of solder balls.

26. (Withdrawn) An integrated circuit package comprising:

a substrate having a plurality of conductive traces;
a plurality of balls disposed on a first surface of said substrate;
a semiconductor die mounted to said substrate such that bumps of said semiconductor die
are electrically connected to said plurality of conductive traces of said substrate;
an overmold material encapsulating said semiconductor die and said balls on said substrate
such that portions of said balls that are disposed farthest from said substrate are exposed; and
a ball grid array disposed on said portions of said balls that are disposed farthest from the
substrate that are exposed, the ball grid array being in electrical connection with said conductive
traces through said plurality of balls.

27. (New) The integrated circuit package according to claim 13, wherein the semiconductor
die is mounted to said substrate via a plurality of solder ball connections.